

PECVD, SIN: Thickness t																
Date		1/6/2014			1/23/2014			2/3/2014			2/18/2014			3/14/2014		
4" Si wafer SIN-1000A		JAW EC-400			JAW EC-400			JAW EC-400			JAW EC-400			JAW EC-400		
		Thickness (Å)	n(632.8)	n(1550)	Thickness (Å)	n(632.8)	n(1550)	Thickness (Å)	n(632.8)	n(1550)	Thickness (Å)	n(632.8)	n(1550)	Thickness (Å)	n(632.8)	n(1550)
Distance(minor cut to 9)×1cm	Minor cut-right															
4cm from the center up	9	1020.11	1.950	1.899	1098.46	1.937	1.892	1039.25	1.940	1.893	1028.13	1.935	1.889	1029.08	1.934	1.887
3cm from the center up	8	1041.55	1.949	1.899	1127.33	1.937	1.891	1048.87	1.940	1.893	1035.79	1.936	1.890	1038.45	1.934	1.888
2cm from the center up	7	1049.48	1.949	1.899	1137.42	1.937	1.891	1050.55	1.939	1.892	1035.27	1.937	1.890	1040.99	1.933	1.887
1cm from the center up	6	1053.79	1.949	1.899	1138.71	1.936	1.891	1048.72	1.938	1.891	1033.31	1.936	1.890	1039.81	1.933	1.887
Center of the wafer	5	1055.25	1.949	1.899	1133.40	1.935	1.890	1046.60	1.937	1.893	1030.66	1.935	1.890	1042.16	1.933	1.887
1cm from the center down	4															
2cm from the center down	3															
3cm from the center down	2															
4cm from the center down	1															
Distance(major cut to 1)×1cm	Major cut-left															
Average		1044.04	1.949	1.899	1127.06	1.936	1.891	1046.80	1.939	1.892	1032.63	1.936	1.890	1038.10	1.933	1.887
Stand. Dev.		14.40			16.59			4.45			3.22			5.23		
3sigma		43.19			49.78			13.34			9.67			15.68		
UCL		1087.23			1176.84			1060.14			1042.30			1053.78		
LCL		1000.84			1077.29			1033.46			1022.96			1022.42		

